



產品特性

Features

High hot and cold impact resisted 耐冷熱衝擊性

Low thermal expansion coefficient 低熱膨脹係數

Anti UV 抗UV

Chemical erosive resisted which can ensure the durability、reliability、security and stability of LED.

耐化學侵蝕性等物理化學優勢特徵，藉以確保LED操作的持久性、可靠性、穩定性與安全性。

產品應用端

Applications

Electronic components: IC、CPU、MOS

LED、M/B、P/S、Heat Sink、

LCD-TV、Notebook PC、PC、Telecom Device、Wireless Hub.....etc.

DDR II Module、DVD Applications、Hand-set applications.....etc.

產品物性

Properties

| 產品性能 Functional Characteristics | CP-20 | CP-57 |
|--|--------------------------------|--------------------------------|
| 絕緣阻抗 Insulation Resistance | >100GΩ (1000VDC, 1 minute) | >10GΩ (1000VDC, 1 minute) |
| 耐電壓值 Dielectric With standing voltage | Ok (1500VAC, 60HZ, 1minute) | Ok (1500VAC, 60HZ, 1minute) |
| 導熱係數 Thermal Conductivity | ≥8W/mk | ≥10W/mk |
| 焊接耐熱性 Solder Heat Resistance | 300°C / 5 sec | 300°C / 5 sec |
| 電極剝離強度 Electrode Tensile Strength | >WB 20N (2Gf) | >WB 20N (2Gf) |
| 密度 Density | ≥3.2g/cm³ | ≥2.5g/cm³ |
| 氣孔率 Porosity | ≤15% | ≤1.5% |
| 符合 RoHS 規範 RoHS Compliant | 是 Yes | 是 Yes |
| 抗折強度 Rending Strength | >WB 100N (10KGf) | >WB 100N (10KGf) |
| 尺寸規格 Dimension | Ø20mm (±2.0mm)x t2.0mm (Max) | Ø53mm (±2.0mm)x t2.0mm (Max) |

Cautions: LED陶瓷電路載板打開包裝後，必須存放在相對溼度30%之環境下。

After open the package, the LED ceramic core print circuit board should be kept at 30% RH or less.